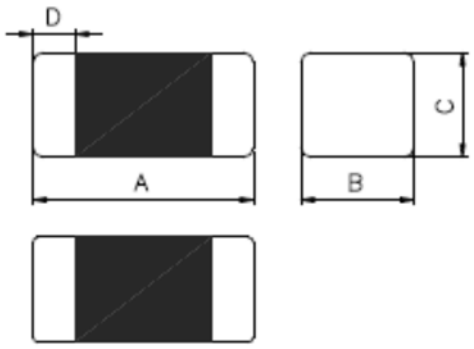
FEATRLRES

- Monolithic inorganic material construction.
- Closed magnetic circuit avoids crosstalk.
- S.M.T. type.
- Suitable for reflow soldering.
- Shapes and dimensions follow E.I.A. spec.
- Available in various sizes.
- Excellent solder ability and heat resistance.
- High reliability.
- 100% Lead(Pb) & Halogen-Free and RoHS compliant.

CONFIGRLRATIONS & DIMENSIONS (unit in mm)



Size	A	B	C	D
HCB1608	1.60±0.15	0.80±0.15	0.60±0.15 0.80±0.15	0.30±0.20

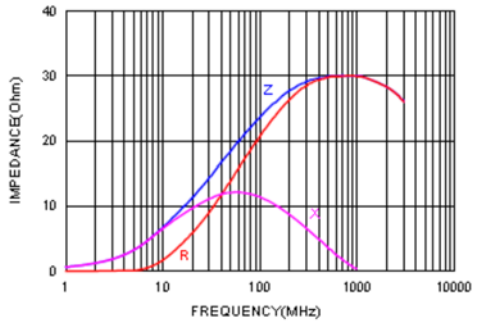
ELECTRICAL CHARACTERISTICS

Part Number	Thickness C size (mm)	Impedance (Ω)	Test Frequency (MHz)	DC Resistance (Ω) max.	Rated Current (mA) max.
HCB1606ZF-260T60	0.60±0.15	26±25%	100	0.01	6000
HCB1608KF-300T30	0.80±0.15	30±25%	100	0.04	3000
HCB1608KF-600T30	0.80±0.15	60±25%	100	0.04	3000
HCB1608KF-800T30	0.80±0.15	80±25%	100	0.04	3000
HCB1608KF-121T20	0.80±0.15	120±25%	100	0.10	2000
HCB1608KF-151T20	0.80±0.15	150±25%	100	0.10	2000
HCB1608KF-221T20	0.80±0.15	220±25%	100	0.10	2000
HCB1608KF-301T10	0.80±0.15	300±25%	100	0.20	1000
HCB1608KF-471T10	0.80±0.15	470±25%	100	0.20	1000
HCB1608KF-601T10	0.80±0.15	600±25%	100	0.20	1000

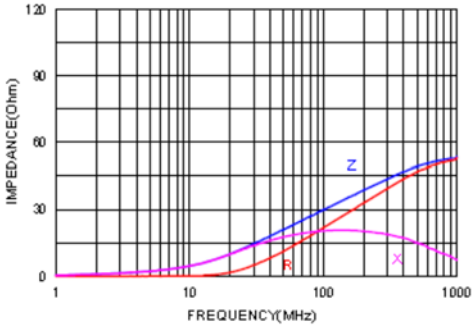
- Rated current: based on temperature rise test
- In compliance with EIA 595

Impedance Frequency Characteristics(Typical)

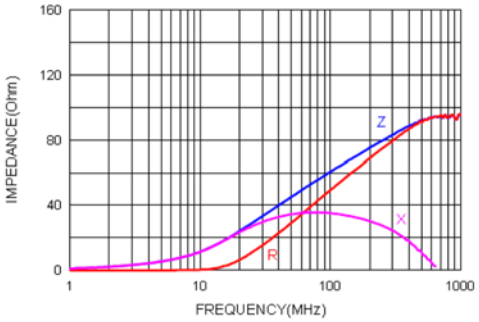
HCB1606ZF-260



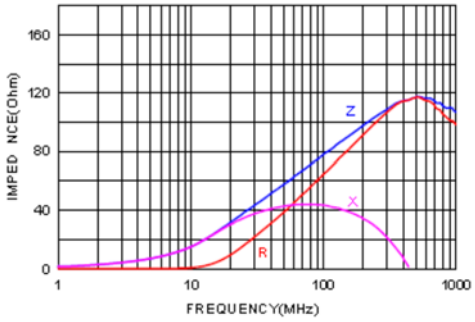
HCB1608KF-300



HCB1608KF-600



HCB1608KF-800



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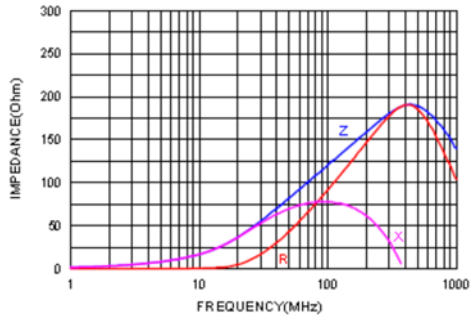

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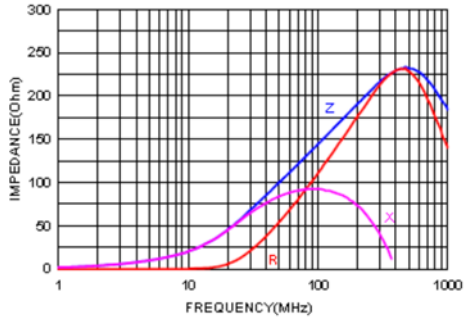
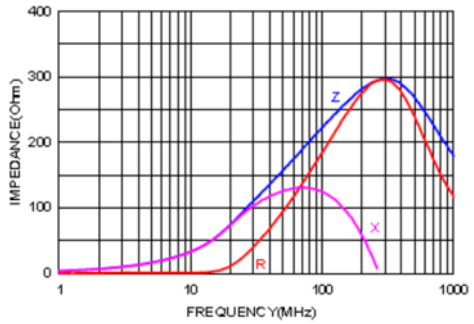
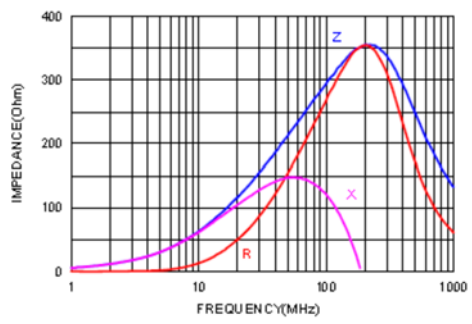


HCB1608KF-221

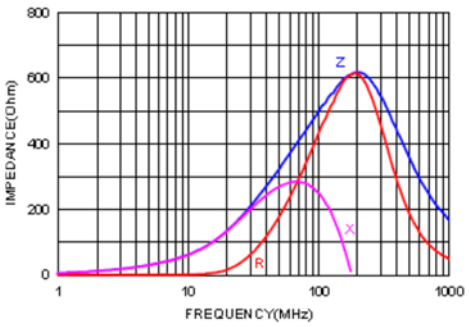


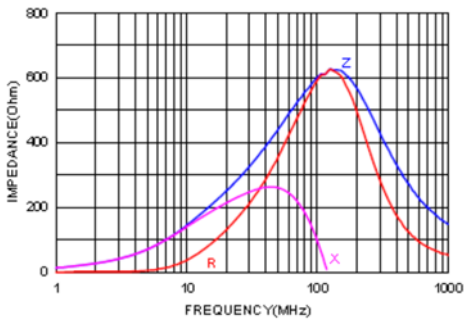
HCB1608KF-301



HCB1608KF-471

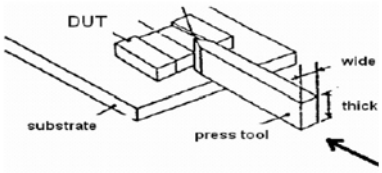
HCB1608KF-601





Reliability and Test Condition

Item	Performance	Test Condition
Operating temperature	-40~+125℃ (Including self - temperature rise)	
Storage temperature	1. -10~+40℃,50~60%RH (Product with taping) 2. -40~+125℃(on board)	
Electrical Performance Test		
Inductance	Refer to standard electrical characteristics list.	HP4284A,CH11025,CH3302,CH1320,CH1320S LCR Meter.
DCR		CH16502,Agilent33420A Micro-Ohm Meter.
Saturation Current (Isat)	Approximately△L30%	Saturation DC Current (Isat) will cause L0 to drop △L(%)
Heat Rated Current (Irms)	Approximately △T40℃	Heat Rated Current (Irms) will cause the coil temperature rise △T(℃). 1.Applied the allowed DC current 2.Temperature measured by digital surface thermometer
Reliability Test		
Life Test	Appearance：No damage. Inductance：within±10% of initial value Q：Shall not exceed the specification value. RDC：within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles) Temperature： 125±2℃(Inductor) Applied current：rated current Duration：1000±12hrs Measured at room temperature after placing for 24±2 hrs
Load Humidity		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Humidity：85±2 % R.H, Temperature：85℃±2℃ Duration：1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs
Moisture Resistance		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles 1. Baked at50℃ for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs. 3. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs,keep at 25℃ for 2 hrs then keep at -10℃ for 3 hrs 4. Keep at 25℃ 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Condition for 1 cycle Step1：-40±2℃ 30±5min Step2：25±2℃ ≦0.5min Step3：125±2℃ 30±5min Number of cycles： 500 Measured at room temperature after placing for 24±2 hrs

<table>
<tr><td>Vibration</td><td></td><td>Oscillation Frequency: 10 ~ 2K ~ 10Hz for 20 minutes
Equipment： Vibration checker
Total Amplitude:1.52mm±10%
Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations)。</td></tr>
<tr><td>Bending</td><td rowspan="2">Appearance：No damage.
Impedance：within±15% of initial value
Inductance：within±10% of initial value
Q：Shall not exceed the specification value.
RDC：within ±15% of initial value and shall not exceed the specification value</td><td>Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm
<0805 inch(2012mm):40x100x0.8mm
Bending depth: >=0805 inch(2012mm):1.2mm
<0805 inch(2012mm):0.8mm
duration of 10 sec.</td></tr>
<tr><td>Shock</td><td>
<table>
<tr><th>Type</th><th>Peak value (g's)</th><th>Normal duration (D) (ms)</th><th>Wave form</th><th>Velocity change (Vi)ft/sec</th></tr>
<tr><td>SMD</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr>
<tr><td>Lead</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr>
</table>
</td></tr>
<tr><td>Solder ability</td><td>More than 95% of the terminal electrode should be covered with solder。</td><td>Preheat: 150℃,60sec.。
Solder: Sn96.5% Ag3% Cu0.5%
Temperature: 245±5℃ 。
Flux for lead free: Rosin. 9.5% 。
Dip time: 4±1sec 。
Depth: completely cover the termination</td></tr>
<tr><td>Resistance to Soldering Heat</td><td rowspan="2">Appearance：No damage.
Impedance：within±15% of initial value
Inductance：within±10% of initial value
Q：Shall not exceed the specification value.
RDC：within ±15% of initial value and shall not exceed the specification value e</td><td>Depth: completely cover the termination
<table>
<tr><th>Temperature(°C)</th><th>Time(s)</th><th>Temperature ramp/immersion and emersion rate</th><th>Number of heat cycles</th></tr>
<tr><td>260 ±5 (solder temp)</td><td>10 ±1</td><td>25mm/s ±6 mm/s</td><td>1</td></tr>
</table>
</td></tr>
<tr><td>Terminal Strength</td><td>Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles
With the component mounted on a PCB with the device to be tested, apply a force(>0805:1kg , <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.
 
</td></tr>
</table>

Note : When there are questions concerning measurement result : measurement shall be made after 48 ± 2 hours of recovery under the standard condition.